

## Getting started with the AEK-COM-ISOSPI1, SPI to isolated SPI dongle based on the L9963T transceiver

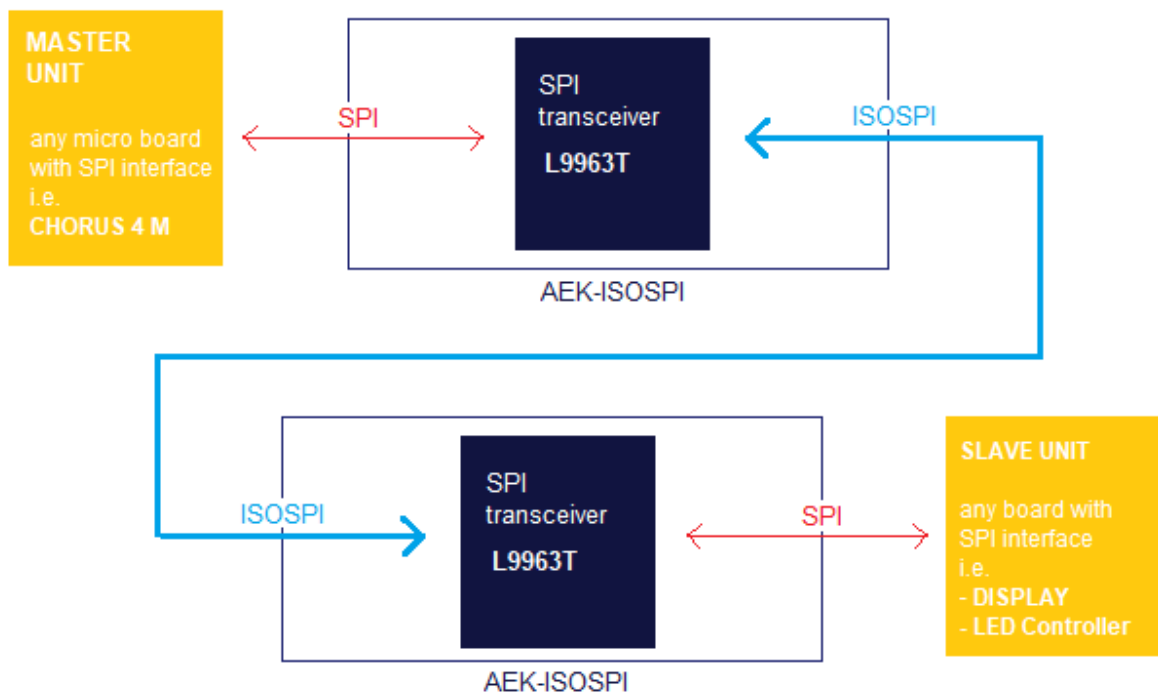
### introduction

One of the most commonly used communication protocols for device control is the SPI one. In the traditional vehicle architecture, the SPI control is used to connect the device with the local microcontroller. With trends moving toward domain / zone architectures, the local microcontroller is disappearing, therefore the protocol has to evolve to cover longer distances to connect the device to the domain / zone controller. In addition, with electrification progressing inside the new vehicles, another desirable feature for such a protocol is the electrical isolation. Based on these requirements, the isolated SPI (ISOSPI) protocol has been defined.

The **AEK-COM-ISOSPI1** board allows converting SPI signals into ISOSPI signals, reducing the number of necessary wires from 4 to 2, and ensuring an isolated differential communication highly immune to noise.

An ISOSPI signal can travel for several meters, maintaining a high ratio between signal and noise.

Figure 1. SPI to ISOSPI conversion block diagram



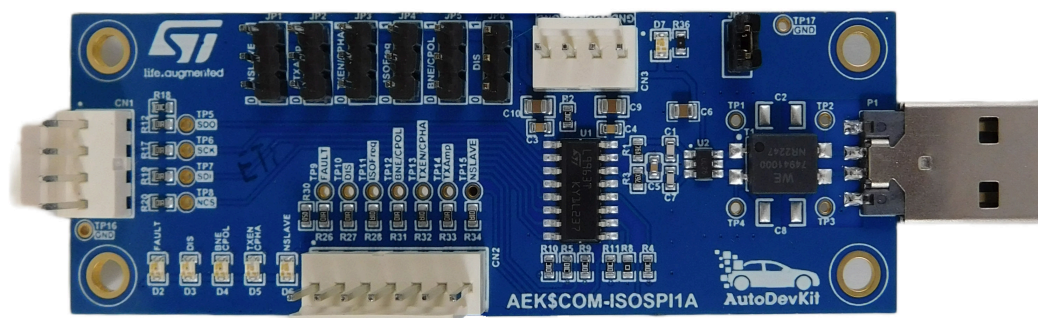
The ISOSPI protocol features differential communication to ensure higher noise immunity and robustness for long distance communication. As the ISOSPI signals can travel for several meters, this protocol is particularly suitable for automotive high voltage applications where electrical isolation is required by the safety standards and the cable length can affect the communication among devices located in distant parts of the vehicle.

The **AEK-COM-ISOSPI1** board is based on the **L9963T** integrated circuit, a general-purpose SPI to isolated SPI bi-directional transceiver, which can transfer communication data incoming from a classical 4-wire based SPI interface to a 2-wire isolated interface (and vice versa).

The **L9963T** hosted on the **AEK-COM-ISOSPI1** can be configured either as a slave or as a master of the SPI bus and supports any protocol of 8-to-64-bit SPI frames. The SPI peripheral can work up to 10 MHz when configured as a slave. The SPI clock frequency can be programmed (250 kHz, 1 MHz, 4 MHz, or 8 MHz) when the device is configured as a master.

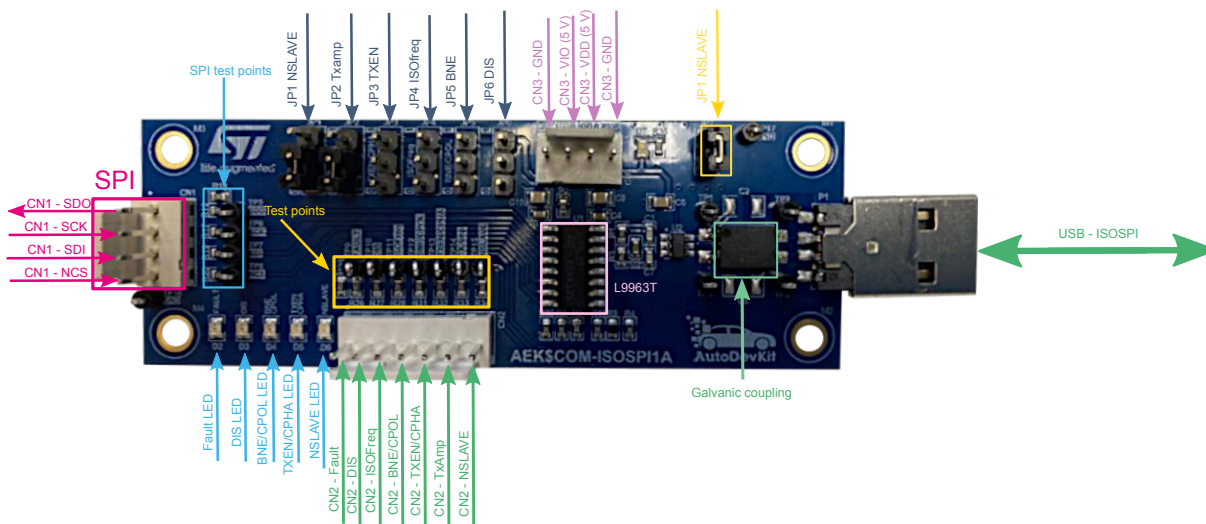
The transceiver is natively compatible with the L9963E IC isolated SPI port, allowing its usage in battery management system (BMS) applications. The basic BMS analog front-end node board is the [AEK-POW-BMS63EN](#). From the microcontroller side, the [AEK-COM-ISOSPI1](#) board can be connected via SPI with SPC5, Stellar and STM32 microcontroller families.

Figure 2. AEK-COM-ISOSPI1



# 1 Hardware overview

**Figure 3. Hardware overview**



The AEK-COM-ISOSPI1 can be programmed through a microcontroller or using jumpers.

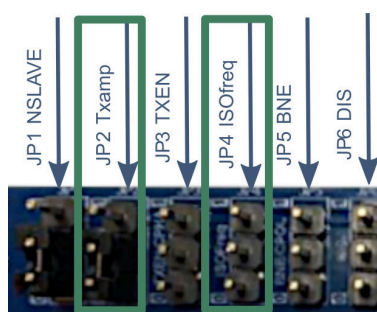
It is necessary to configure two parameters:

- The signal frequency
- The signal amplitude

To send a signal over a long distance, it is necessary to lower the frequency. Tune the signal frequency and amplitude according to the distance that you intend to reach.

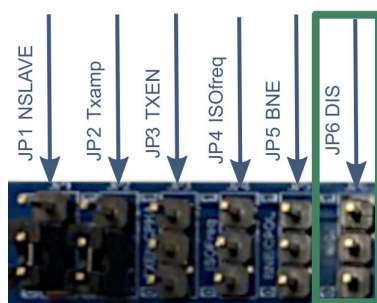
To set these parameters, use the jumpers for Txamp and IsoFreq. They can be arranged in two positions: closing pin 2 and pin 3 or closing pin 1 and pin 2.

**Figure 4. Jumper configuration**

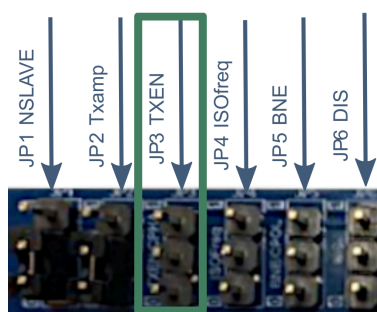


Amplitude and frequency can be set through the microcontroller GPIO on the AEK-COM-ISOSPI1 DIS pin.

You can enable or disable the AEK-COM-ISOSPI1 through jumpers on the DIS pin or through the microcontroller.

**Figure 5. Jumpers on DIS pin**


To enable this pin, use jumpers on TXEN or program the microcontroller to set the TXEN pin.

**Figure 6. TXEN pin**


NSLAVE can assume the value 0 (for the slave configuration) or 1 (for the master configuration).

## 1.1 L9963T

The L9963T is a general purpose SPI to isolated SPI transceiver IC, which acts as a bridge among devices located in different voltage domains.

The L9963T can transfer communication data incoming from a classical four-wire based SPI interface to a two-wire isolated interface (and vice versa).

The device can be configured either as slave or as master of the SPI bus and supports any protocol made of SPI frames (8 to 64 bits).

L9963T integrates two communication interfaces:

- a SPI interface used for the local data exchange with a master MCU or with a generic slave IC
- an isolated SPI interface for global/local isolated communication with another L9963T or with an ISOLine compatible device (such as L9963E).

The SPI peripheral can work up to 10 MHz when configured as a slave.

The SPI clock frequency can be programmed (250 kHz, 1 MHz, 4 MHz, or 8 MHz) when configured as a master.

The isolated SPI peripheral features two different operating modes: slow at 333 kbps and fast at 2.66 Mbps.

The L9963T is compatible with both 3.3 V and 5 V logic.

## 1.2 Pin description

### 1.2.1 SPI

SDO, SCK, SDI, NCS pins implement the SPI peripheral, whose configuration depends on the NSLAVE value latched at the first power-up:

- SDI is always configured as a digital input. It is internally pulled down with RIN\_PD to generate a 0x0 frame in case of pin loss (leading to CRC violation in safety applications). Its buffer is enabled only in the Normal state.

- SDO is always configured as a digital output. Its buffer is enabled only if NCS is asserted. An external pull up/pull down resistor defines the inactive level of the line.
- SCK, NCS can be either configured as a digital input (NSLAVE = 0, SPI slave) or as a digital output (NSLAVE = 1, SPI master).

The selective enable/disable of the buffers helps reducing the power consumption of the device when the SPI works at high frequencies.

### 1.2.2 CPOL and CPHA

The following table shows CPOL and CPHA settings according to different SPI modes.

**Table 1. SPI mode configuration**

SPI mode	CPOL	CPHA	Shift SCK-Edge	Capture SCK-Edge
0	0	0	Falling	Rising
1	0	1	Rising	Falling
2	1	0	Rising	Falling
3	1	1	Falling	Rising

Clock polarity has no significant effect on the transfer format. The commutation of this bit causes the inversion of the clock signal (active high becomes active low and idle low becomes idle high). Clock phase settings, however, allow selecting one of two different transfer times. The master configures the clock polarity (CPOL) and the clock phase (CPHA) to be aligned with the slave device requirements. These parameters determine when data need to be changed according to the clock line and which is the clock level when the clock is not active.

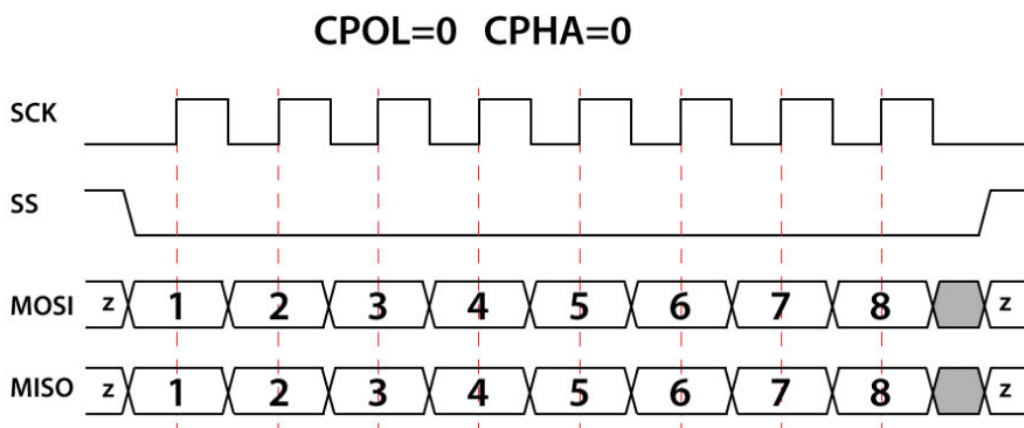
CPOL assigns a clock level when the clock is not active. The clock signal (SCK) can be inverted (CPOL = 1) or not activated (CPOL = 0). For the inverted clock signal, the first clock edge is falling. For the first not inverted clock signal, the first clock edge is rising.

CPHA is used to move the capture phase. If CPHA = 0, data are sampled on the leading (first) clock edge.

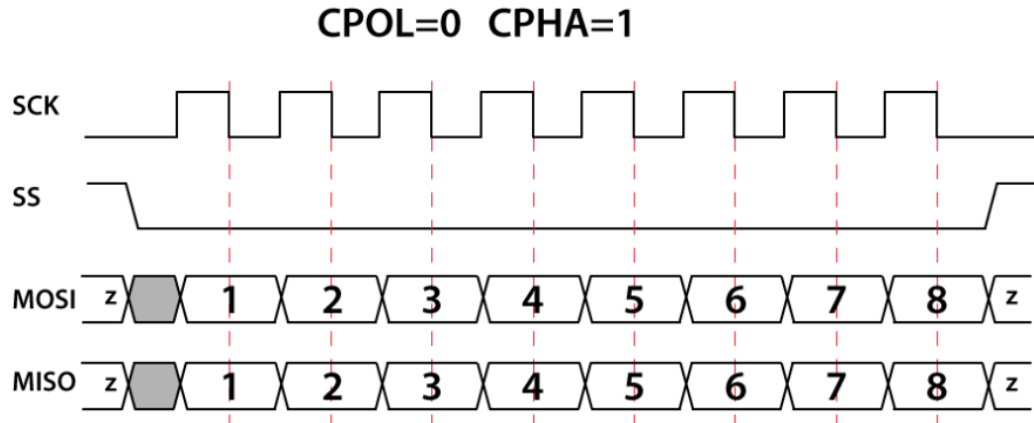
There are four possible modes that can be used in a SPI protocol:

1. For CPOL = 0, the clock basic value is zero. For CPHA = 0, data are sampled on the clock rising edge and are shifted on the clock falling edge.

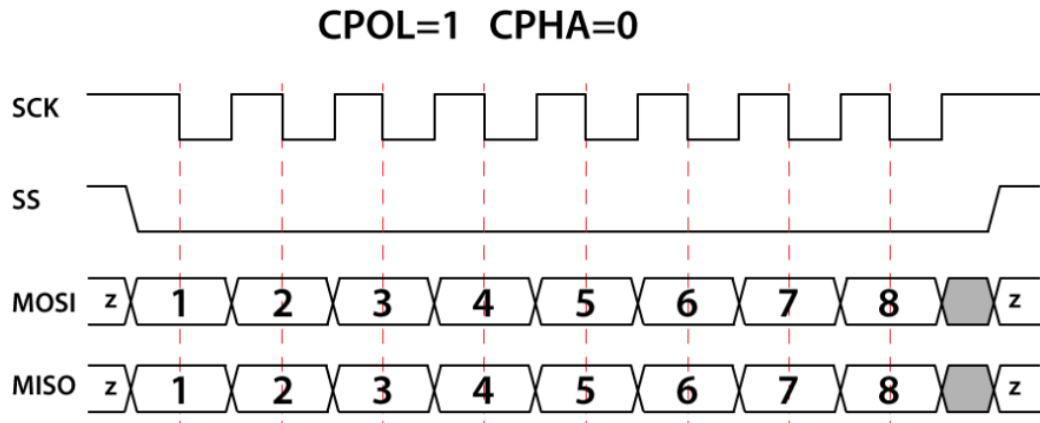
**Figure 7. TXEN pin**



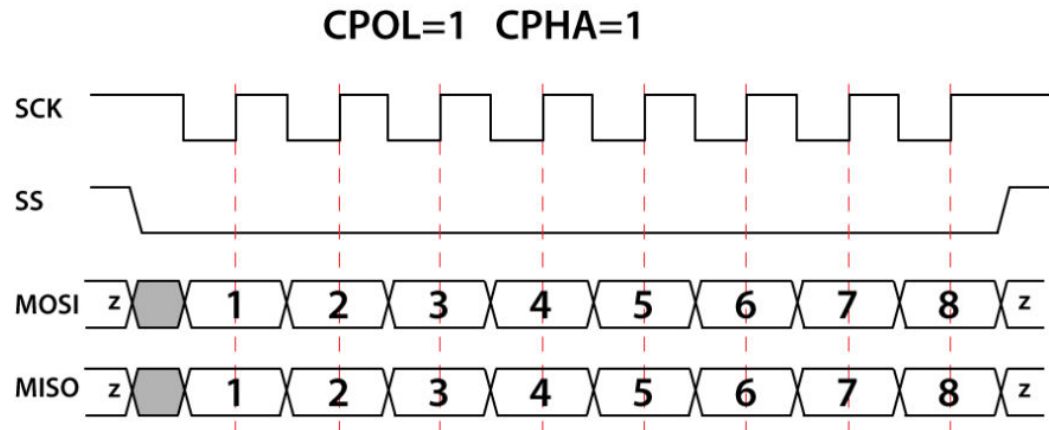
2. For CPOL = 0, the clock basic value is zero. For CPHA = 1, data are sampled on the clock falling edge and are shifted on the clock rising edge.

**Figure 8. SPI protocol mode 1**


3. For CPOL = 1, the clock basic value is 1. For CPHA = 0, data are sampled on the clock rising edge and are shifted on the clock falling edge.

**Figure 9. SPI protocol mode 2**


4. For CPOL = 1, the clock basic value is 1. For CPHA = 1, data are sampled on the clock falling edge and shifted on the clock rising edge.

**Figure 10. SPI mode 3**


### 1.2.3 NSLAVE

The NSLAVE pin is latched by the standby logic in the Trimming & Config Latch state. It must be either shorted to VDD or to GND. The internal pull-down is enabled only while in Trimming & Config Latch state. This allows reducing power consumption. Once Trimming & Config Latch state is left, the NSLAVE input buffer is permanently disabled, since it is no longer needed.

NSLAVE selects the SPI master (NSLAVE = 1) or slave (NSLAVE = 0) operation and determines the digital I/Os configuration.

To increase immunity to BCI and guarantee a correct latch of the NSLAVE pin during each power-up, the input is filtered with an integrated RC filter.

### 1.2.4 DIS

DIS is a digital input-output pin that features an internal pull-up resistor towards V3V3\_STBY. Its purpose is to be driven by open-drain outputs. Its functionality is summarized as follows:

- Input: is an active high disabling input driven by the MCU:
  - When DIS is released by the MCU longer than TRC\_DELAY+TDIS\_DEGLITCH, the device starts the Go To Sleep sequence that brings the L9963T to the Stand-by state.
  - When DIS is pulled down by the MCU longer than TRC\_DELAY + (1/fSTBY\_OSC), the device moves from the Stand-by state to the Regulators enabling state and then to the Normal state.
- Output: when L9963T is in the Stand-by state, and a wake-up event by isolated SPI occurs, it moves to the Regulators enabling state and then to the Normal state. Once the latter is reached, DIS is internally pulled down by logic for TDIS\_PULLDOWN to trigger an interrupt in the MCU or a wake-up event. After TDIS\_PULLDOWN expires, DIS is released and, if not kept low by an external source, the L9963T moves back to the Stand-by state. To protect DIS internal open drain driver in case of external short to VDD, a current limitation circuitry limits the current to IDIS\_LIM.

### 1.2.5 BNE/CPOL

BNE/CPOL is a digital input/output pin whose configuration depends on the value of NSLAVE latched during Trimming & Config Latch:

- When NSLAVE = 0 (slave configuration), this pin acts as BNE (buffer not empty) digital output. Its purpose is to implement interrupt-based communication with the MCU. When asserted high, the RX queue stores at least one frame.



- When NSLAVE = 1 (master configuration), this pin acts as a digital input for the selection of CPOL (clock polarity):
  - CPOL = 0 (shorted to GND) implies that the clock inactive level (when NCS is high) is low.
  - CPOL = 1 (shorted to VDD) implies that the clock inactive level is high. The internal pull-down is always enabled during Trimming & Config Latch and in Normal state. The BNE output buffer is disabled if NSLAVE = 1 has been latched during Trimming & Config Latch. The CPOL input buffer is permanently enabled.

In case NSLAVE = 0 has been latched during Trimming & Config Latch, BNE output buffer is kept enabled while in the Normal state. A short to GND/VDD detection is implemented to protect the BNE output buffer. If the value forced on the BNE output buffer differs from the one sampled by the CPOL input buffer for more than TBNE\_SHORT\_DET, the BNE output buffer is put into HiZ. Automatic re-engagement of the BNE output buffer occurs upon the next wakeup sequence (MCU needs to toggle DIS pin).

### 1.2.6 TXEN/CPHA

TXEN\_CPHA is a digital input pin whose configuration depends on the value of NSLAVE latched during Trimming & Config Latch:

- When NSLAVE = 0 (slave configuration) the pin works as a transmitter enabling TXEN:
  - The MCU should release TXEN (or pull it up actively) prior to NCS assertion to enable the transmission of the data from SDI input buffer to the TX queue (and then to the isolated SPI interface).
  - If the communication protocol does not feature any burst read capability, each command sent by the master unit generates a single answer from the addressed slave unit. Hence, the TXEN pin can be connected to VDD to keep the transmitter permanently enabled.
  - In case of burst read operations, where the user software has to empty the RX queue without transmitting any frame on the isolated SPI, the TXEN input must be pulled down before beginning the burst read.
  - Even if data on the SDI line is discarded while TXEN = 0, it is highly recommended that the MCU sends dummy frames (or intentionally corrupted frames) on the SDI line during the burst read. In the event of TXEN stuck high, such frames generate errors according to the implemented communication protocol.  
To avoid chopping frames currently being transmitted, the TXEN pin is latched upon NCS assertion. Therefore, it must be stable at least TTXEN\_DEGLITCH + TTXEN\_SETUP before NCS assertion. Moreover, TXEN must be kept stable TTXEN\_HOLD after NCS assertion to fulfil hold time constraints.
- When NSLAVE = 1 (master configuration), this pin acts as a digital input for the selection of CPHA (clock phase). It is latched during Trimming & Config Latch and should be therefore either shorted to GND or to VDD:
  - CPHA = 0 (shorted to GND) implies that the SDI signal is sampled upon the first SCK edge after NCS assertion.
  - CPHA = 1 (shorted to VDD) implies that the SDI signal is sampled upon the second SCK edge after NCS assertion.

The internal pull-up is enabled when L9963T is in Trimming & Config Latch and is kept enabled in the Normal state to allow a correct driving of the pin by the open-drain output of the MCU. Moreover, in case of pin loss, the pull-up guarantees a limp home operation where the transmitter is always enabled. To guarantee stand-by consumption requirements, the pull-up is disabled while in the Stand-by state.

### 1.2.7 TXAMP

TXAMP pin can be used to switch between the two possible ISOLine TX amplitude configurations:

- TXAMP = 0 selects low TX amplitude (RDIFF\_ISO\_OUTL)
- TXAMP = 1 selects high TX amplitude (RDIFF\_ISO\_OUTH)

TXAMP sampling depends on the device state and configuration.



**Table 2. TXAMP sampling strategy**

L9963T state	L9963T configuration	TXAMP sampling	Note
Normal state	Slave (NSLAVE = 0)	The TXAMP pin is latched upon NCS assertion. Therefore, it must be stable at least TTXAMP_DEGLITCH + TTXAMP_SETUP before NCS assertion. Moreover, TXAMP must be kept stable TTXAMP_HOLD after NCS assertion in order to fulfil hold time constraints.	In case several SPI frames are being pushed into the TX queue, the setting applied depends on the last one latched (no pipelining supported).
		The new amplitude setting is applied to the TX interface after the SPI frame has been completely transmitted over the isolated SPI interface. This allows Managing ISOFREQ And TXAMP Pins For Communicating With L9963.	
Normal state	Master (NSLAVE = 1)	The TXAMP setting is simply resynchronized (TTXAMP_SETUP and TTXAMP_HOLD requirements still apply) and deglitched (TTXAMP_DEGLITCH filter still present), but it is not latched upon NCS assertion. The new amplitude setting is applied to the TX interface as soon as the transmission of the SPI frame over the isolated SPI interface begins.	In case several SPI frames are being pushed into the TX queue, the setting applied depends on the last one latched (no pipelining supported).
Stand-by state	Slave/Master (NSLAVE = X)	The new TXAMP setting is latched during the wakeup sequence. Hence, the TXAMP pin shall be stable TTXAMP_SETUP before the DIS high → low transition is applied and shall not change during TWAKEUP.	-
Reset state	Slave/Master (NSLAVE = X)	The initial TXAMP setting is latched during the first power up sequence. Hence, the TXAMP pin shall be stable before VDD is applied and shall not change during TFIRST_POWERUP.	-

It is recommended to apply the same TXAMP settings to all the devices communicating on the bus, to keep a constant SNR in every communication phase.

To meet stand-by consumption requirements, MCU must release the open drain output connected to TXAMP while L9963T is in the Stand-by state.

### 1.2.8 SPICLKFreq

SPICLKFreq pin is an analog input, compared to four thresholds by a set of analog comparators.

An external resistor RCLKPD must be connected between SPICLKFreq and GND, in order to generate a voltage  $VSPICLKFreq = RCLKPD * ISPICLKFreqPU$ .

The code obtained from these 4 comparator outputs is latched in the Trimming & Config Latch to determine the SPI clock frequency when L9963T works in master mode (NSLAVE = 1).

In the AEK-COM-ISOSPI1 the SPICLKFreq is fixed at 250 kHz.

### 1.2.9 ISOP and ISOM

The isolated SPI interface allows units with different ground levels and/or on different boards to communicate with each other. Physically, the interface is based on twisted-pair wire.

**Table 3. Pins used as isolated SPI**

L9963T Pin	SPI function	Configuration
ISOP	positive differential input/output	Analog Input/Output
ISOM	negative differential input/output	Analog Input/Output

**Table 4. Isolated SPI quick look**

Parameter	Description
Protocol	Half-Duplex / Out of frame
Max. Bit-rate	2.66 Mbps (high speed configuration, ISOFREQ = 1)

Parameter	Description
333 kbps (low speed configuration, ISOFREQ = 0, default if pin is left floating)	

The transmission line on the isolated SPI exploits a single twisted pair. Communication data is transmitted/received over a pulse-shaped signal, in a half-duplex protocol.

Line bit rate can be selected by programming the ISOFREQ device pin.

A single bit is made of a pulse time (TPULSE) followed by two pauses (2TPULSE):

- TPULSE = 2TBIT\_HIGH\_LOW\_FAST for the high speed configuration (ISOFREQ = 1)
- TPULSE = 2TBIT\_HIGH\_LOW\_SLOW for the low speed configuration (ISOFREQ = 0)

An isolated receiver and transmitter are connected to the couple of pins and ISOP/M. Depending on the communication phase, they can be enabled or disabled.

The receiver can convert a differential input signal into a single ended signal that is provided to the logic:

- While in Normal state, to guarantee correct communication, the input common mode must stand within VCM\_ISO\_IN limits.
- When in Stand-by state, the ISOP and ISOM pins are not biased with a common mode. If the device receives a series of differential pulses longer than NMIN\_ISO\_WAKEUP\_EDGES, a wakeup condition is triggered. Pulse amplitude must be higher than Wakeup\_thr to be counted.

### 1.2.10

#### ISOFREQ

ISOFREQ pin is a digital input used to switch ISOline bit rate:

- ISOFREQ = 1 selects fast operation: bit time is TBIT\_LENGTH\_FAST
- ISOFREQ = 0 selects slow operation: bit time is TBIT\_LENGTH\_SLOW

ISOFREQ sampling depends on device state and configuration.

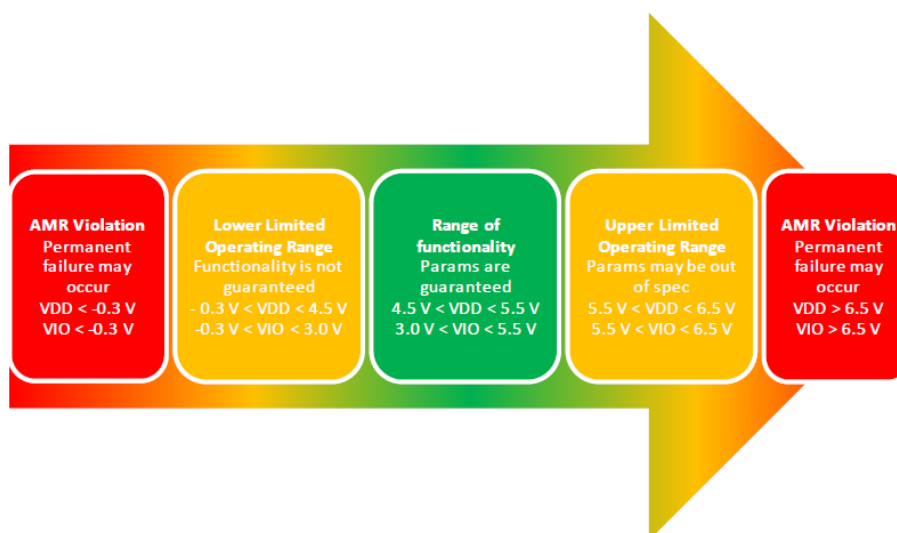
**Table 5. ISOFREQ sampling strategy**

L9963T state	L9963T configuration	ISOFREQ sampling	Note
Normal state	Slave (NSLAVE = 0)	<p>The ISOFREQ pin is latched upon NCS assertion. Therefore, it must be stable at least TISOFREQ_DEGLITCH + TISOFREQ_SETUP before NCS assertion. Moreover, ISOFREQ must be kept stable TISOFREQ_HOLD after NCS assertion in order to fulfil hold time constraints.</p> <p>The new bit rate setting is immediately applied to the RX interface, while it is applied to the TX interface after the SPI frame has been completely transmitted over the isolated SPI interface. This allows Managing ISOFREQ And TXAMP Pins For Communicating With L9963</p>	In case several SPI frames are being pushed into the TX queue, the setting applied once the TX interface is in idle depends on the last one latched (no pipelining supported).
	Master (NSLAVE = 1)	The ISOFREQ setting is simply resynchronized (TISOFREQ_SETUP and TISOFREQ_HOLD requirements still apply) and deglitched (TISOFREQ_DEGLITCH filter still present), but it is not latched upon NCS assertion.	
Stand-by state	Slave/Master (NSLAVE = X)	The new ISOFREQ setting is latched during the wake up sequence. Hence, the ISOFREQ pin shall be stable TISOFREQ_SETUP before the DIS high → low transition is applied and shall not change during TWAKEUP.	-
Reset state	Slave/Master (NSLAVE = X)	The initial ISOFREQ setting is latched during the first power up sequence. Hence, the ISOFREQ pin shall be stable before VDD is applied and shall not change during TFIRST_POWERUP.	-

## 2 Power supply

The figure below lists the product power supply ranges.

**Figure 11. Power supply ranges**

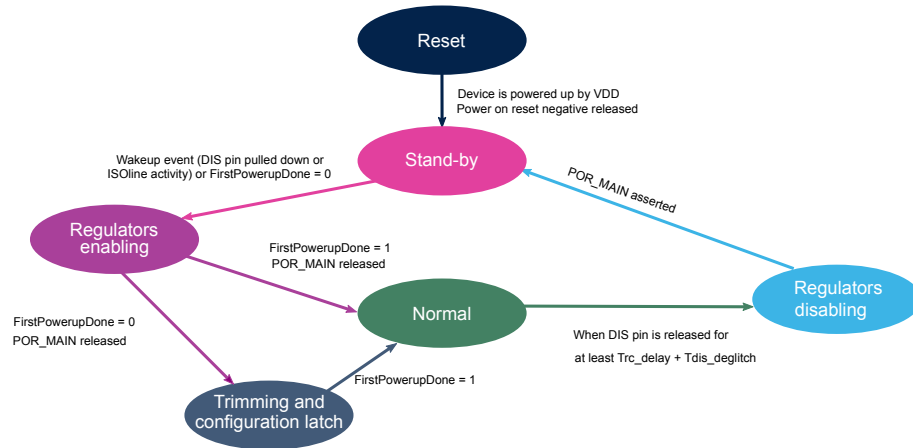


- Within the range of functionality, the part operates as specified and without parameter deviations. All the functionalities and the electrical parameters are guaranteed.
- If either the upper or the lower limited operating range is reached, the device may not operate properly. Only a limited set of functionalities and electrical parameters are guaranteed. However, neither damage nor parameter deviation occurs, and the device operates properly once returned to the range of functionality.
- If the absolute maximum rating (AMR) is violated, permanent damage or parametric deviation may occur.

**Note:** All voltages are related to the potential at substrate ground GND.

### 3 Finite state machine

**Figure 12. Finite state machine**



Different state transition sequences occur according to the following different scenarios:

- First power-up: Reset state → Stand-by state → Regulators enabling state → Trimming & Config Latch → Normal state. The first power-up sequence lasts TFIRST\_POWERUP.
- Wake up: Stand-by state → Regulators enabling state → Normal state. In case of wakeup triggered by DIS release, the state transition is the same. The wakeup sequence lasts TWAKEUP.
- Go To Sleep: Normal state → Regulators disabling state → Stand-by state. The go to sleep sequence lasts TGO2SLP.

#### 3.1 Reset state

When VDD is below the value triggering the power-up, the device is not functional. No operation is possible while under reset.

#### 3.2 Stand-by state

This state is entered either from the Reset state or from the Regulators disabling state:

- Transition from the Regulators disabling state only occurs upon DIS low → high transition while L9963T is in the Normal state. DIS input signal is filtered in both analog (TRC\_DELAY) and digital (TDIS DEGLITCH) domains.
- Transition from Reset state only occurs upon first power-up, after POR\_STBY release.

While in standby, the logic checks the FirstPowerupDone latch, whose reset value is '0' upon the first power-up:

- In case FirstPowerupDone = 0, the first power-up has never been accomplished. Hence, the device moves to the Regulators enabling state, regardless of any wakeup source state.
- In case FirstPowerupDone = 1, the first power-up has already been accomplished. Hence, the device is kept in the Stand-by state and eventual transitions are determined by the wakeup sources.

When a wakeup source is asserted, it triggers the wakeup sequence that moves the L9963T to the Regulators enabling state. The possible wakeup sources are:

- The de-assertion of DIS pin, pulled down by an external open drain source (TRC\_DELAY + (1/fSTBY\_OSC) filter applies).
- The detection of at least NMIN\_ISO\_WUP\_EDGES pulses within TWAKEUP\_TIMEOUT\_ISO on the ISOLine.

#### 3.3 Regulators enabling state

This is a transitional state reached from the Stand-by state.

While L9963T is in this state, it enables the V3V3 regulator and the OSCI\_MAIN.

During this process lasting TWAKEUP, the device must not be sensitive to DIS pin, SPI interface, and ISOLine sources. Once a wakeup sequence starts, it cannot be interrupted.

The Regulators enabling state is left upon Fs\_MAIN release. The next state depends on the FirstPowerupDone latch:

- In case FirstPowerupDone = 0, the first power-up has never been accomplished. Hence, the device moves to the Trimming & Config Latch.
- In case FirstPowerupDone = 1, the first power-up has already been accomplished. Hence, the device moves to the Normal state.

### 3.4 Trimming and configuration latch state

This state is entered from the Regulators enabling state the first time the device is powered up (FirstPowerupDone = 0).

While in this state, the device must:

- Download the OTP data.
- Latch the configuration inputs (NSLAVE, CPHA, CPOL, SPICLKFREQ), storing them into the STBY logic registers.

SPICLKFREQ comes from a set of comparators that must be checked by an internal BIST before latching the comparator output. In case the BIST fails, a default 0 value (corresponding to the slowest SPI configuration) must be stored into the related stand-by internal register.

Stand-by registers hold their value as long as the POR\_STBY stays de-asserted.

While in this state, L9963T is not sensitive to SPI/VIF activity and wakeup conditions (DIS/VIF).

This phase must safely go to an end and may last a maximum time interval of TSETUP\_LATCH.

After this phase finishes, the FirstPowerupDone latch is set to "1" in the standby logic and the device moves to the Normal state.

### 3.5 Normal state

While in this state, all references and main logic are powered. Both communication interfaces are ready for data TX/RX activity.

This state is reached either from Trimming & Config Latch (first power up) or from Regulators enabling state (following a normal wakeup sequence):

- When woken up by an activity on the ISOline, once the Normal state is reached, the device must neglect the DIS pin value (even if it is high) and, on the contrary, it must drive the DIS pin low for TDIS\_PULLDOWN (DIS is an input/output pin). Such a strategy allows generating an interrupt into the MCU, or triggering a wakeup. Once TDIS\_PULLDOWN expires, L9963T releases the DIS pull down and unmask the DIS deglitched input. If the MCU has been correctly woken up, it pulls down the DIS pin externally, so that L9963T is kept in the Normal state.

Otherwise, DIS is found asserted (high) and the IC moves back to the Regulators disabling state.

- When woken up by the DIS pin itself, the device must start listening to the deglitched DIS pin as soon as it enters the Normal state.

To detect a "Go to Sleep" condition, the DIS pin status must be constantly monitored through a synchronous deglitch filter (TDIS\_DEGLITCH, implemented in the main logic through the main oscillator).

Its effect is cascaded to the passive RC filter placed on the input comparator (TRC\_DELAY).

When DIS is sensed "high", the main logic raises a signal that triggers the "Go To Sleep" sequence in the IC FSM. L9963T moves to the Regulators disabling state and finally to the Stand-by state.

### 3.6 Regulators disabling state

This is a transitional state reached from the Normal state during a "Go To Sleep" sequence.

While in this state, the V3V3\_MAIN regulator and main oscillator enable signals are de-asserted, leading to POR\_MAIN assertion and reset of the main logic.

POR\_MAIN assertion marks the transition to the Stand-by state.

Even if the main logic is still alive while the device is in the Regulators disabling state, it must not be sensitive to external pins (wakeup sources, COM interfaces, etc.). Once started, a "Go To Sleep" sequence cannot be interrupted.

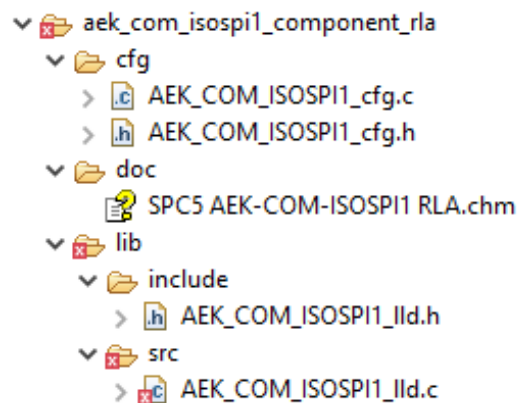
## 4 AutoDevKit ecosystem

The application development employing the [AEK-COM-ISOSPI1](#) board takes full advantage of the [AutoDevKit](#) ecosystem, whose basic components are:

- [AutoDevKit Studio IDE \(STSW-AUTODEVKIT\)](#)
- [PLS UDE](#) and [OpenOCD](#) programmers and debuggers

### 4.1 Component folder structure

**Figure 13. AEK-COM-ISOSPI1 component folder structure**



The `cfg` folder contains all the configuration files.

The `doc` folder contains the doxygen documentation.

The `lib` folder contains the component header and source files.

### 4.2 Software component architecture (AEK-COM-ISOSP1 Component RLA)

The following image shows the architecture of the software components that we created for the [AEK-COM-ISOSPI1](#) evaluation board, which consists of the following layer:

- `AEK-COM-ISOSP1_Ild`

**Figure 14. Software architecture**



The `AEK-COM-ISOSP1_Ild` contains all the APIs:

- To configure L9963T transceiver as a master or a slave SPI.
- To configure amplitude and frequency of the ISOSP1 signal.
- To enable/disable the L9963T transceiver.
- To enable/disable ISOSP1 communication.

## 5 Available APIs

The APIs listed in the following tables are declared in the “AEK\_COM\_ISOSPI1\_1ld.h” file.

**Table 6. APIs for the AEK-COM-ISOSPI1**

API name	Description
I9963t_PALWritePad (ISOSPI_Driver_t I9963t, ISOSPI_pal_ch_t I9963t_pal_ch, uint8_t value)	Sets the logical state of a pad of the AEK-COM-ISOSPI1.
I9963t_PALReadPad (ISOSPI_Driver_t I9963t, ISOSPI_pal_ch_t I9963t_pal_ch)	Reads the logical state of a pad of the AEK-COM-ISOSPI1.
AEK_COM_ISOSPI_SetAsSlave (ISOSPI_DEVICE dev)	Sets the AEK-COM-ISOSPI1 as a slave.
AEK_COM_ISOSPI_EnableTransceiverComm (ISOSPI_DEVICE dev)	Enables the transceiver communication.
AEK_COM_ISOSPI_DisableTransceiverComm (ISOSPI_DEVICE dev)	Disables the transceiver communication.
AEK_COM_ISOSPI_SetAsMaster (ISOSPI_DEVICE dev)	Sets the AEK-COM-ISOSPI1 as a master.
AEK_COM_ISOSPI_SampleSPI_firstclk (ISOSPI_DEVICE dev)	Samples the SPI first clock.
AEK_COM_ISOSPI_SampleSPI_secondclk (ISOSPI_DEVICE dev)	Samples the SPI second clock.
AEK_COM_ISOSPI_CPOL_low (ISOSPI_DEVICE dev)	Sets CPOL low (this function can be used only if NSLAVE = 1).
AEK_COM_ISOSPI_CPOL_high (ISOSPI_DEVICE dev)	Sets CPOL high (this function can be used only if NSLAVE = 1).
AEK_COM_ISOSPI_EnableTransceiver (ISOSPI_DEVICE dev)	Enables the transceiver.
AEK_COM_ISOSPI_DisableTransceiver (ISOSPI_DEVICE dev)	Disables the transceiver.
AEK_COM_ISOSPI_SetISOCCommSlow (ISOSPI_DEVICE dev)	Sets the ISOFREQ to low (this establishes a slow communication equal to 333 kHz).
AEK_COM_ISOSPI_SetISOCCommFast (ISOSPI_DEVICE dev)	Sets the ISOFREQ to high (this establishes a fast communication equal to 2.66 MHz).
AEK_COM_ISOSPI_ISOTX_Attenuate (ISOSPI_DEVICE dev)	Sets TXAMP to low (SPI signal not amplified).
AEK_COM_ISOSPI_ISOTX_Amplify (ISOSPI_DEVICE dev)	Sets TXAMP to high (SPI signal amplified).
AEK_COM_ISOSPI_GetFault (ISOSPI_DEVICE dev)	Reads the value of the FAULT pin and updates a fault flag, which is included in the driver data structure (ISOSPI_Driver_t).
AEK_COM_ISOSPI_ConfigMode (ISOSPI_DEVICE dev, ISOSPI_mode_t I9963t_mode)	Configures the NSLAVE according to the user interface configuration.
AEK_COM_ISOSPI_ConfigISOFreq (ISOSPI_DEVICE dev, ISOSPI_iso_freq_t I9963t_iso_freq)	Configures the ISOFREQ according to the user interface configuration.
AEK_COM_ISOSPI_ConfigISOAmp (ISOSPI_DEVICE dev, ISOSPI_tx_amp_t I9963t_tx_amp)	Configures the TXAMP according to the user interface configuration.
AEK_COM_ISOSPI_ConfigCPOL (ISOSPI_DEVICE dev, ISOSPI_master_cpol_t I9963t_cpol)	Configures the CPOL according to the user interface configuration.
AEK_COM_ISOSPI_ConfigCPHA (ISOSPI_DEVICE dev, ISOSPI_master_cpha_t I9963t_cpha)	Configures the CPHA according to the user interface configuration.
config_Transceiver (ISOSPI_Driver_t driver)	Comprehensive API, invoking ConfigMode, ConfigISOFreq, ConfigISOAmp, ConfigCPOL, ConfigCPHA functions.
slave_example_config (ISOSPI_DEVICE dev)	Slave configuration function example, which drives every configuration pin of the transceiver setting it as a slave.
master_example_config (ISOSPI_DEVICE dev)	Master configuration function example, which drives every configuration pin of the transceiver setting it as a master.



## 6 Using AEK-COM-ISOSP1 within AutoDevKit

In this example, we created an application for the AEK-COM-ISOSP1 configured as a slave transceiver. We used the [AEK-MCU-C4MLIT1](#) as the microcontroller board.

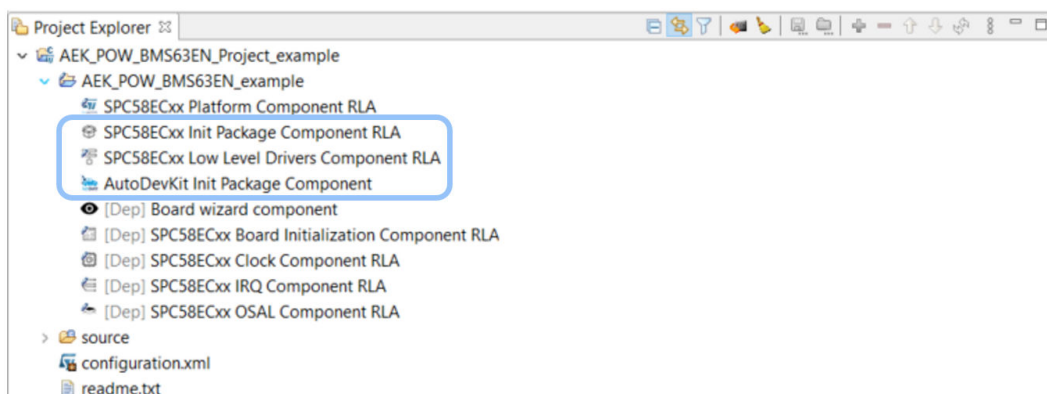
To recreate this scenario, follow the procedure below.

**Step 1.** Create a new SPC5-STUDIO application for the SPC58EC series microcontroller and add the following components:

- SPC58ECxx Init Package Component RLA
- SPC58ECxx Low Level Drivers Component RLA
- AutoDevKit Init Package Component

These components must be added immediately, or the other components will not be visible.

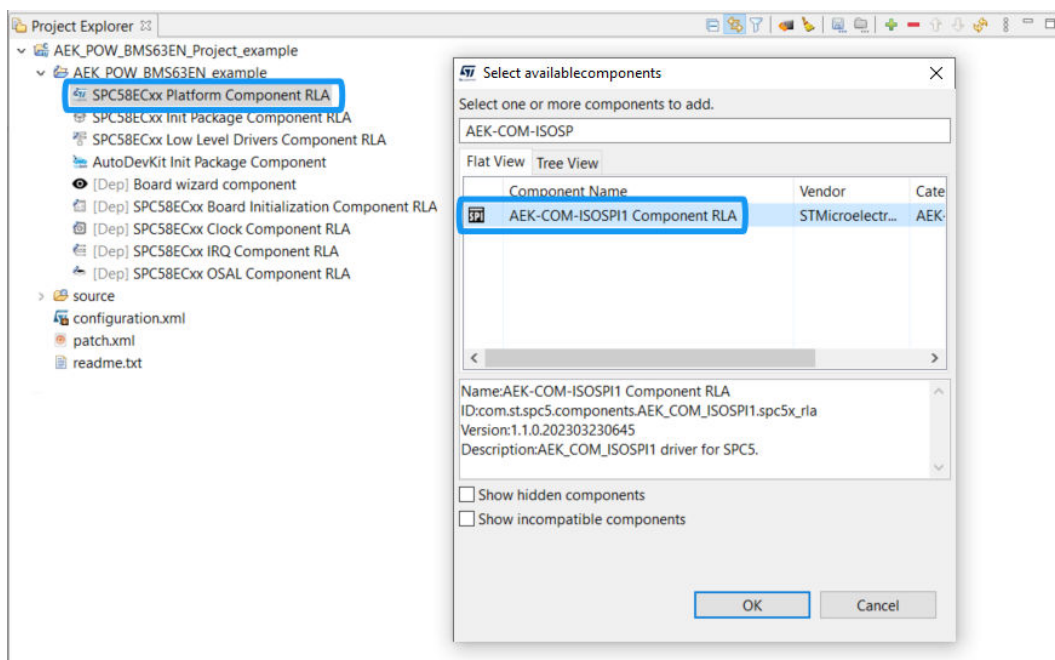
Figure 15. Adding components



**Step 2.** Add the following additional components

- AEK-COM-ISOSP1 Component RLA

Figure 16. Adding components



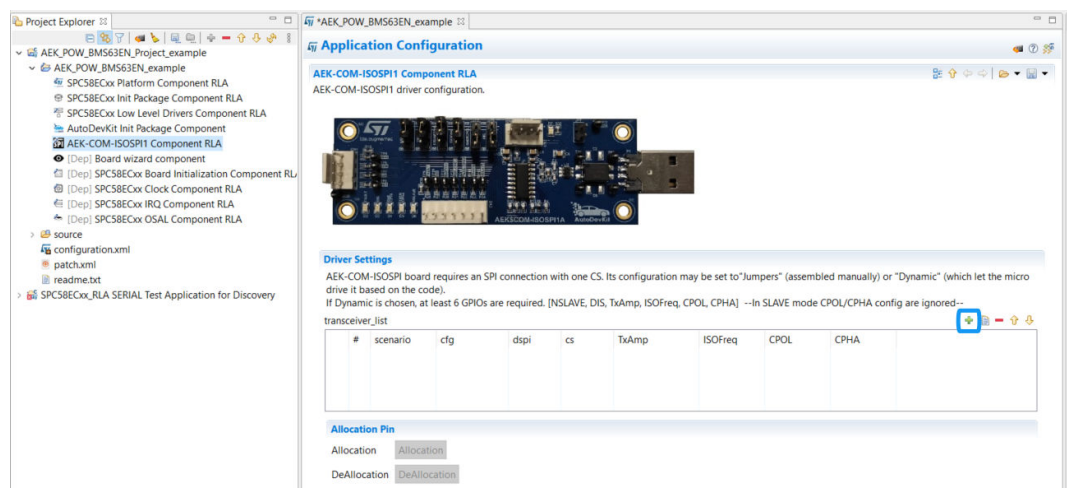
**Step 3.** Select [AEK-COM-ISOSP1 Component RLA] to open the [Application Configuration] window.

**Figure 17. Adding components**



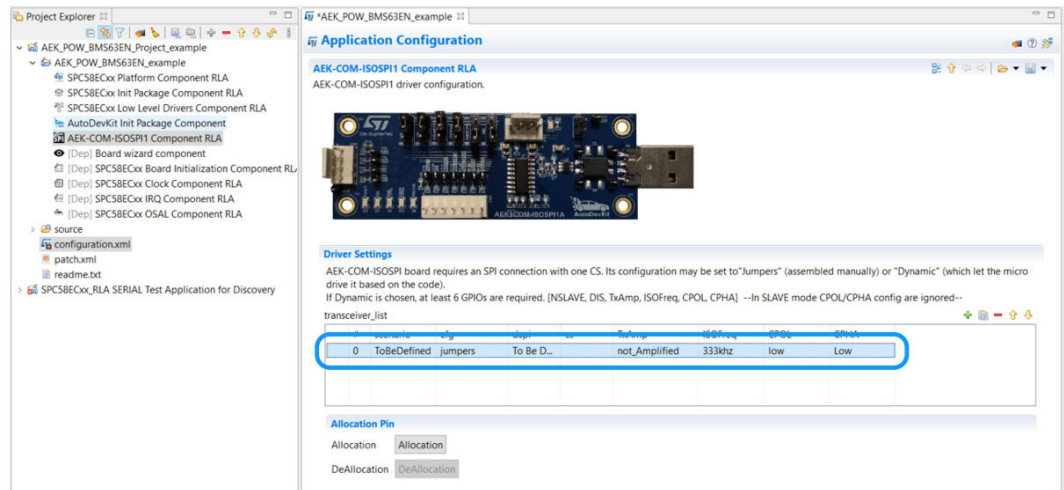
**Step 4.** Click on [+] to add a new element to the board list.

**Figure 18. Adding components**



**Step 5.** Double-click on the newly added element to configure the board.

**Figure 19. AEK-COM-ISOP11 configuration**



Step 6.

- Select scenario “two”
- Select DSPI and CS
- Select the “cfg” configuration as “micro”
- Select TxAmp as “not amplified”
- Select ISOFreq as “333 KHz”
- Select Master Clock Frequency as “5 MHz”
- Select CPOL and CPHA as “low”

Figure 20. Available scenarios

Application Configuration

AEK-COM-ISOSP11 Component RLA

AEK-COM-ISOSP11 driver configuration.

Transceiver\_configuration [0]

From this screen you can define the configuration of a Transceiver board. It may be changed via SW in runtime. SPC5 will allocate also the DIS pad, which enables the transceiver if low. In case of “Dynamic” configuration, 6 GPIOs are required. [NSLAVE, DIS, TxAmp, ISOFreq, CPOL, CPHA]

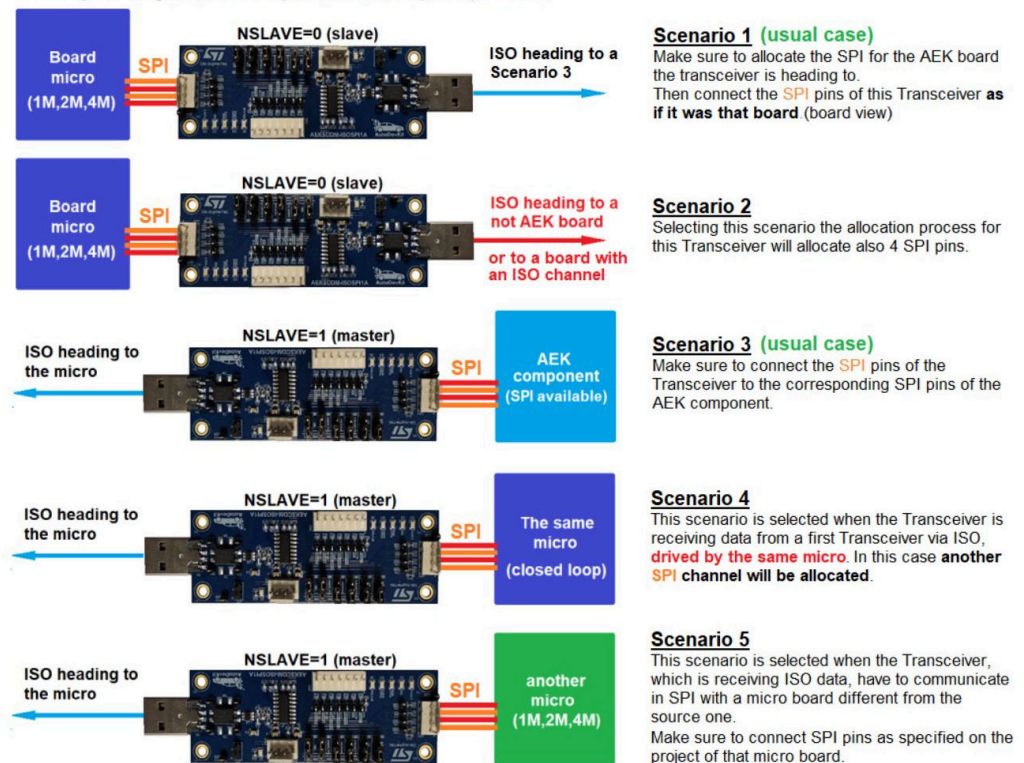


Figure 21. AEK-COM-ISOP11: scenario number two configuration

scenario: two

dspi: DSPI 0

cs: CS0 0

Configuration type: If "Jumpers" is Checked, the only pad drivable by the micro will be DIS. The others have to be set manually using Jumpers. In case of Dynamic configuration, at least 6 GPIOs are required. [NSLAVE, DIS, TxAmp, ISOFreq, CPOL, CPHA]

cfg:

☐ jumpers

☒ micro

TxAmp=Low signal not amplified.  
TxAmp=High signal amplified (suitable for long cables).

TxAmp: not\_Amplified

ISOFreq=Low 333khz.  
ISOFreq=High 2.66Mhz.

ISOFreq: 333khz

When working as Master, the generated clock frequency may be changed based on the value of the resistance R6  
R6 = 0 ohm -> 250khz  
R6 = 9.3 Kohm -> 1Mhz  
R6 = 16,2 Kohm -> 4Mhz  
R6 = 22.9 Kohm -> 8Mhz

masterclock\_frequency: 5Mhz

CPOL=low/high define clock polarity when Mode=Master

CPOL: low

CPHA=low/high define clock phase when Mode=Master

CPHA: Low

Step 7. Click on the "Allocation" button to allocate the AEK-POW-ISOSP11 component.

Figure 22. Component allocation

Project Explorer: AEK\_POW\_BMS63EN\_example

- AEK\_POW\_BMS63EN\_example
  - SPC58ECx Platform Component RLA
  - SPC58ECx Init Package Component RLA
  - SPC58ECx Low Level Drivers Component RLA
  - AutoDevKit Init Package Component
  - AEK-COM-ISOSP11 Component RLA
    - [Dep] Board wizard component
    - [Dep] SPC58ECx Board Initialization Component RLA
    - [Dep] SPC58ECx Clock Component RLA
    - [Dep] SPC58ECx IRQ Component RLA
    - [Dep] SPC58ECx OSAL Component RLA
  - source
    - configuration.xml
    - patch.xml
    - readme.txt
  - SPC58ECx\_RLA SERIAL Test Application for Discovery

Application Configuration

AEK-COM-ISOSP11 Component RLA  
AEK-COM-ISOSP11 driver configuration.

Driver Settings

AEK-COM-ISOSP11 board requires an SPI connection with one CS. Its configuration may be set to "Jumpers" (assembled manually) or "Dynamic" (which let the micro drive it based on the code).  
If Dynamic is chosen, at least 6 GPIOs are required. [NSLAVE, DIS, TxAmp, ISOFreq, CPOL, CPHA] --In SLAVE mode CPOL/CPHA config are ignored--

transceiver\_list

#	scenario	cfg	dspi	cs	TxAmp	ISOFreq	CPOL	CPHA
0	two	micro	DSPI 0	CS0 0	not_Amplified	333khz	low	Low

Allocation Pin

Allocation: Allocation

DeAllocation: DeAllocation

Step 8. Click on "Board View" to see Hardware connection between the AEK-MCU-C4MLIT1 board and the AEK-COM-ISOSP1 dongle.

Figure 23. Hardware connection through the Board View

Editors for 'Application Name'

Here are the available editors on the selected application

- PinMap editor
- SPC584B 2M clock tree
- SPC584B 2M board view

SPC58ECx 4M board view

SPC58ECx Discovery

AEK-MCU-C4MLIT1

Connector	Pin Name	Connector
CN1	NC60	D21
CN1	NC36	D20
CN1	MD	B10
CN1	MD	B11
CN1	MD	B12
CN1	MD	B13
CN1	MD	B14
CN1	MD	B15
CN1	MD	B16
CN1	MD	B17
CN1	MD	B18
CN1	MD	B19
CN1	MD	B20
CN1	MD	B21
CN1	MD	B22
CN1	MD	B23
CN1	MD	B24
CN1	MD	B25
CN1	MD	B26
CN1	MD	B27
CN1	MD	B28
CN1	MD	B29
CN1	MD	B30
CN1	MD	B31
CN1	MD	B32
CN1	MD	B33
CN1	MD	B34
CN1	MD	B35
CN1	MD	B36
CN1	MD	B37
CN1	MD	B38
CN1	MD	B39
CN1	MD	B40
CN1	MD	B41
CN1	MD	B42
CN1	MD	B43
CN1	MD	B44
CN1	MD	B45
CN1	MD	B46
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CN1	MD	B87
CN1	MD	B88
CN1	MD	B89
CN1	MD	B90
CN1	MD	B91
CN1	MD	B92
CN1	MD	B93
CN1	MD	B94
CN1	MD	B95
CN1	MD	B96
CN1	MD	B97
CN1	MD	B98
CN1	MD	B99
CN1	MD	B100

**Step 9.** Create your main application example as follows:

```
#include "components.h"
#include "AEK_COM_ISOSPI1_lld.h"
/*
 * Application entry point.
 */
int main(void) {

    static uint8_t txbuf[512];
    static uint8_t rxbuf[512];

    /* Initialization of all the imported components in the order specified in
       the application wizard. The function is generated automatically.*/
    componentsInit();
    irqIsrEnable();

    /*Set AEK_COM_ISOSPI1 as spi slave*/
    AEK_COM_ISOSPI_SetAsSlave(ISOSPI_DEV0);

    /*Set AEK_COM_ISOSPI1 as ISO fast speed*/
    AEK_COM_ISOSPI_SetISOCCommFast(ISOSPI_DEV0);

    /*Set AEK_COM_ISOSPI1 as High Amplitude*/
    AEK_COM_ISOSPI_ISOTX_Amplify(ISOSPI_DEV0);

    /*Enable AEK_COM_ISOSPI1*/
    AEK_COM_ISOSPI_EnableTransceiver(ISOSPI_DEV0);

    /*Start SPI low level driver*/
    spi_lld_start(AEK_ISOSPI_ARRAY_DRIVER[0].spip, AEK_ISOSPI_ARRAY_DRIVER[0].spicfgp);
}

/* Application main loop.*/
for ( ; ; ) {
    /*Enable ISO communication AEK_COM_ISOSPI1*/
    AEK_COM_ISOSPI_EnableTransceiverComm(ISOSPI_DEV0);

    /*Send/Receive 512 byte via ISOSPI protocol*/
    spi_lld_exchange(AEK_ISOSPI_ARRAY_DRIVER[0].spip, 512, txbuf, rxbuf);

    /*Disable ISO communication AEK_COM_ISOSPI1*/
    AEK_COM_ISOSPI_DisableTransceiverComm(ISOSPI_DEV0);

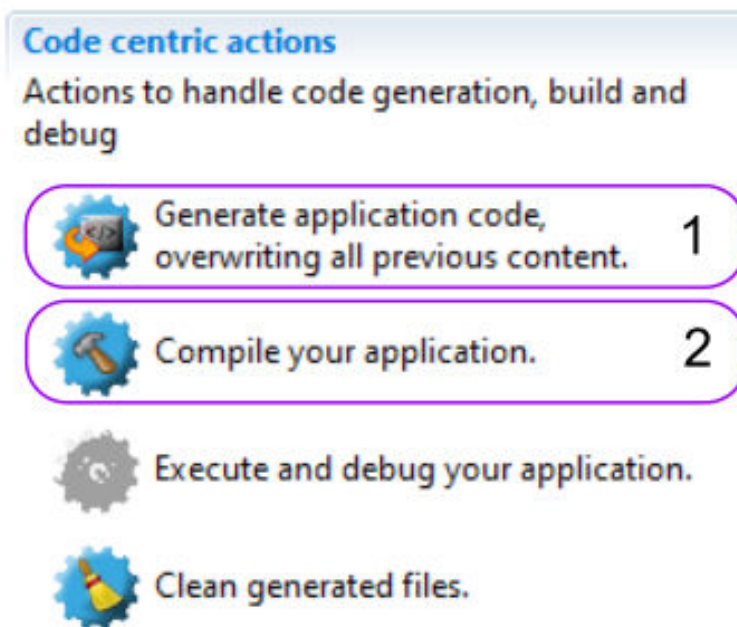
    /*Wait for 500 msec*/
    osalThreadDelayMilliseconds(500);
}
}
```

**Note:** This application is able to send and receive 512 bytes via ISOSPI protocol by using the AEK-COM-ISOSPI1 board with L9963T.



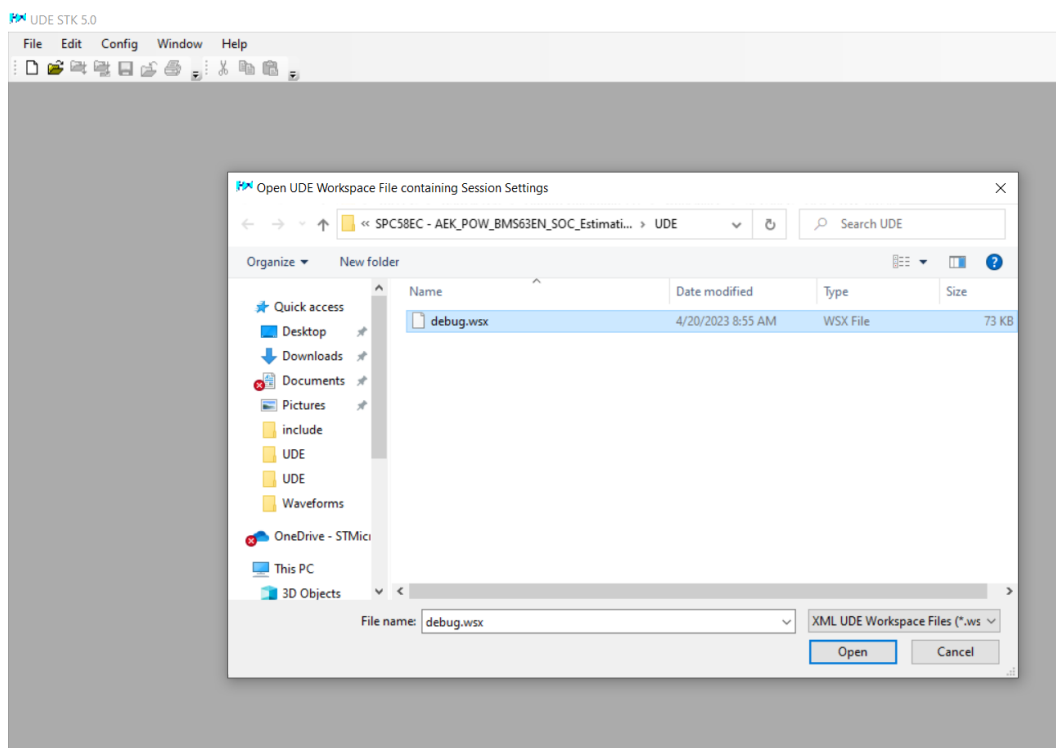
**Step 10.** Generate and compile your application.

**Figure 24.** Application generation menu



**Step 11.** Open “UDE Starterkit” and import the “.wsx” file with workspace to flash your application.

**Figure 25.** UDE initial window



**Step 12.** Switch on your AEK-MCU-C4MLIT1 and enjoy your AEK-COM-ISOSP1 application.



## 6.1 Available demos for AEK-COM-ISOSP1

In the Autodevkit release 2.1.0 (or higher), there are the following available demos for the AEK-COM-ISOSP1:

- **SPC58EC - ISOSPI1\_LEDdriver test application for discovery**, which is a demo application for the AEK-MCU-C4MLIT1 to drive an AEK-LED-21DISM1 LED driver board with the AEK-COM-ISOSP1;
- **SPC582B - ISOSPI1\_LEDdriver test application for discovery**, which is a demo application for the AEK-MCU-C1MLIT1 to drive an AEK-LED-21DISM1 LED driver board with AEK-COM-ISOSP1.

### 6.1.1 AEK-COM-ISOSP1 demo with the AEK-LED-21DISM1 LED driver

This application is based on the SPC58EC microcontroller. It is able to send multiple ReadROMRegisters to read the content of ROM\_DEVICE\_N4 (0x05) register of the AEK-LED-21DISM1 LED driver via ISOSP1 protocol by using the AEK-COM-ISOSP1 board transceiver configured as a SPI slave.

Find below the main code for the *SPC58EC - ISOSPI1\_LEDdriver test application for discovery* demo:

```
#include "components.h"
#include "AEK_COM_ISOSPI1_llb.h"
#include "AEK_COM_ISOSPI1_cfg.h"
#include "AEK_LED_21DISM1.h"
#include "spi_llb.h"
#include "spi_llb_cfg.h"
#include <stdio.h>
#include <stdlib.h>
#include <math.h>
/*
 * Application entry point.
 */
int main(void) {

    uint8_t Data[4];

    /* Initialization of all the imported components in the order specified in
       the application wizard. The function is generated automatically.*/
    componentsInit();

    /* Enable Interrupts. */
    irqIsrEnable();

    /* Enabling both the AEK-COM-ISOSP1 transceiver */
    AEK_COM_ISOSPI_EnableTransceiver (ISOSPI_DEV0);
    AEK_COM_ISOSPI_EnableTransceiver (ISOSPI_DEV1);

    /* Reset AEK-LED-21DISM1 */
    ClearAndTrigger(AEK_LED_21DISM1_DEV0);
    osalThreadDelayMicroseconds(50);

    /*Activate Boost 1 and 2 on AEK-LED-21DISM1*/
    ActivateBoostBuckOne(AEK_LED_21DISM1_DEV0);
    ActivateBoostBuckTwo(AEK_LED_21DISM1_DEV0);
    osalThreadDelayMicroseconds(50);

    /*Activate Buck 1 and 2 on AEK-LED-21DISM1*/
    ActivateBuckDev(AEK_LED_21DISM1_DEV0,DEV1, BUCK1);
    ActivateBuckDev(AEK_LED_21DISM1_DEV0,DEV1, BUCK2);

    /* Application main loop.*/
    for ( ; ; ) {
        /* Asks multiple times to the AEK-LED-21DISM1 the value of one of ROM_DEVICE_N4 */
        AEK_LED_21DISM1drv_ReadROMRegisterSPC(AEK_LED_21DISM1_DEV0, ROM_DEVICE_N4 ,Data);
        AEK_LED_21DISM1drv_ReadROMRegisterSPC(AEK_LED_21DISM1_DEV0, ROM_DEVICE_N4 ,Data);
        AEK_LED_21DISM1drv_ReadROMRegisterSPC(AEK_LED_21DISM1_DEV0, ROM_DEVICE_N4 ,Data);
        AEK_LED_21DISM1drv_ReadROMRegisterSPC(AEK_LED_21DISM1_DEV0, ROM_DEVICE_N4 ,Data);
        AEK_LED_21DISM1drv_ReadROMRegisterSPC(AEK_LED_21DISM1_DEV0, ROM_DEVICE_N4 ,Data);
        osalThreadDelayMicroseconds(50);
    }
}
```

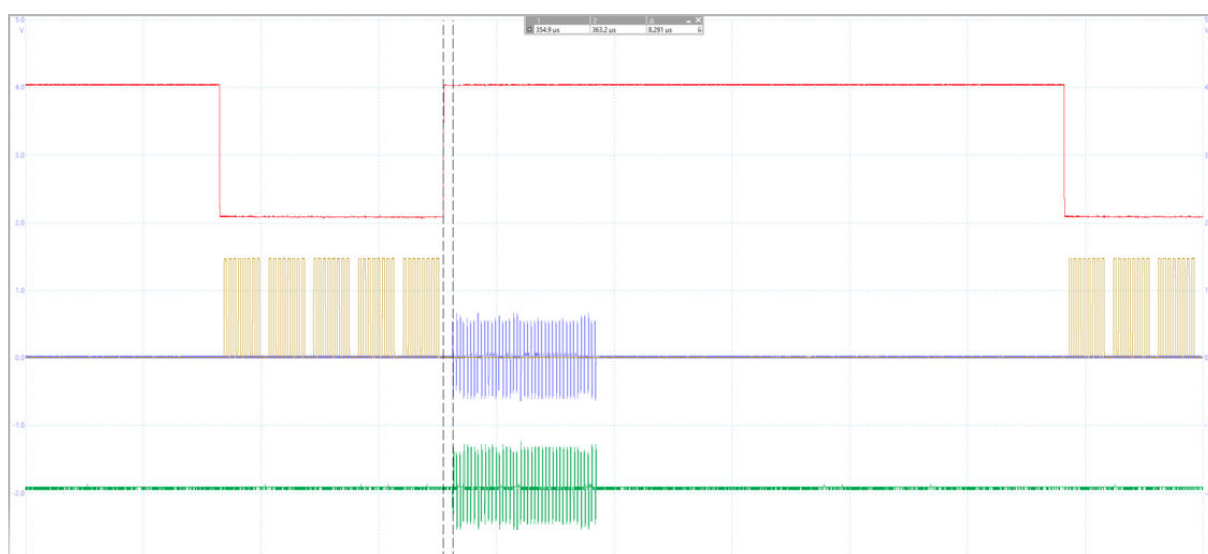
## 7 Test results

The waveforms of the figure below show how a generic SPI signal is converted into an ISOSPI signal through the L9963T.

In particular:

- The first and second waveforms from the bottom represent ISOL and ISOH signals, respectively, which are ISOSPI signals generated by the L9963T
- The middle waveform represents the CLK signal at a frequency of 250 KHz
- The top waveform represents the NCS signal: the Chip Select is falling at the beginning of the SPI packet and rising at the end of the SPI packet

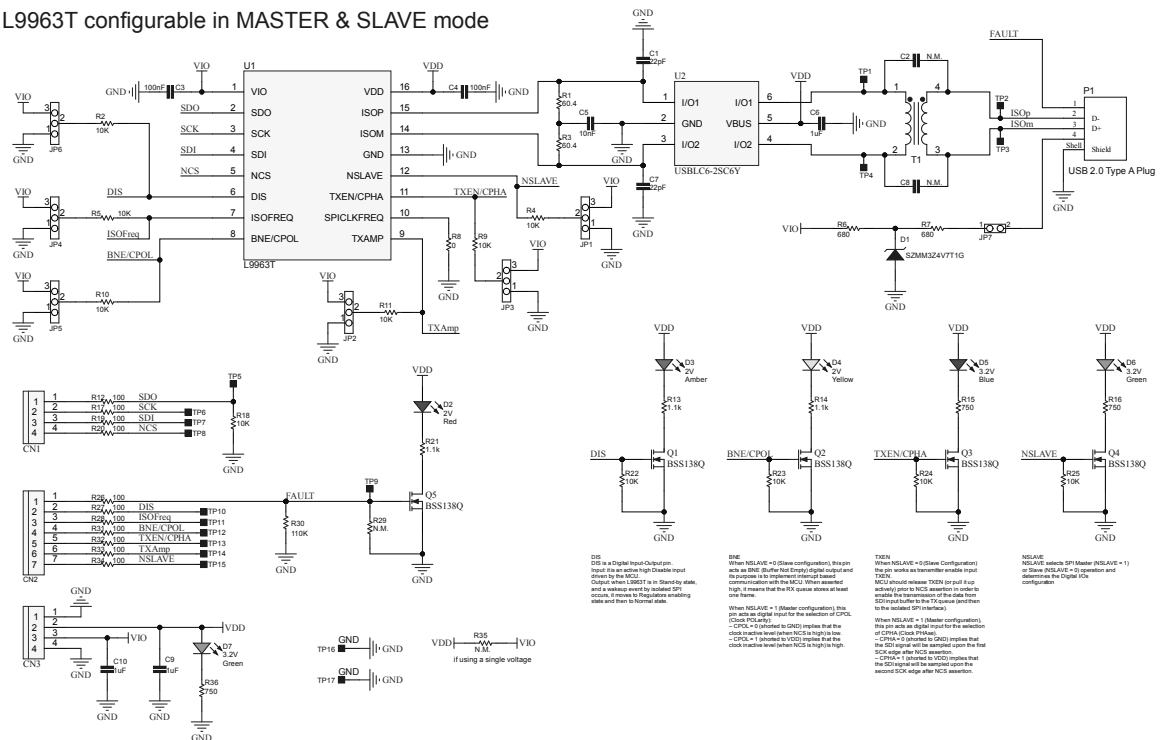
**Figure 26. Test result waveforms**



## 8 Schematic diagram

Figure 27. AEK-COM-ISOSPI1 circuit schematic

L9963T configurable in MASTER & SLAVE mode



## 9 Bill of materials

**Table 7. AEK-COM-ISOSPI1 bill of materials**

Item	Q.ty	Ref.	Part/Value	Description	Manufacturer	Order code
1	2	C1, C7	22pF	0603 - 50V - NP0 Class I	WE	885012006053
2	2	C2, C8	N.M.	1206	N.M.	N.M.
3	2	C3, C4	100nF	0603 - 50V - X7R Class II	WE	885012206095
4	1	C5	10nF	0603 - 50V - X7R Class II	WE	885012206089
5	3	C6, C9, C10	1uF	0805 - 50V - X7R Class II	WE	885012207103
6	2	CN1, CN3		2.54mm - 1 row - KK254 - Male	WE	61900411121
7	1	CN2		2.54mm - 1 row - KK254 - Male	WE	61900711121
8	1	D1	SZMM3Z4V7T1G	4.7V Zener Voltage Regulators, 300mW	Onsemi	SZMM3Z4V7T1G
9	1	D2	Red	0805 - Led Red - 2V	WE	150080RS75000
10	1	D3	Amber	0805 - Led Amber - 2V	WE	150080AS75000
11	1	D4	Yellow	0805 - Led Yellow - 2V	WE	150080YS75000
12	1	D5	Blue	0805 - Led Blue - 3.2V	WE	150080BS75000
13	2	D6, D7	Green	0805 - Led Green - 3.2V	WE	150080GS75000
14	6	JP1, JP2, JP3, JP4, JP5, JP6		THT Vertical 3 pins Header, Pitch 2.54 mm, Single Row	WE	61300311121
15	1	JP7		2.54mm - 1 row	WE	61300211121
16	1	P1	629004113921	USB 2.0 Type A, Plug, Horizontal, SMT, with Clip	WE	629004113921
17	5	Q1, Q2, Q3, Q4, Q5	BSS138Q	N-Channel Enhancement Mosfet	NEXPERIA	BSS138Q-7-F
18	2	R1, R3	60.4	0603 - $\pm 1\%$ - 0.1W	Panasonic	ERJ3EKF60R4V
19	11	R2, R4, R5, R9, R10, R11, R18, R22, R23, R24, R25	10K	0603 - $\pm 1\%$ - 0.2W	Panasonic	ERJP03F1002V
20	2	R6, R7	680	0603 - $\pm 1\%$ - 0.25W	Panasonic	ERJPA3F6800V
21	1	R8	0	0603 - $\pm 1\%$ - 0.1W	Panasonic	ERJ3GEY0R00V
22	11	R12, R17, R19, R20, R26, R27, R28, R31, R32, R33, R34	100	0603 - $\pm 1\%$ - 0.25W	Panasonic	ERJPA3F1000V
23	3	R13, R14, R21	1.1k	0603 - $\pm 1\%$ - 0.25W	Panasonic	ERJPA3F1101V
24	3	R15, R16, R36	750	0603 - $\pm 1\%$ - 0.25W	Panasonic	ERJUP3D7500V
25	1	R29	N.M.	0603	N.M.	N.M.
26	1	R30	110K	0603 - $\pm 1\%$ - 0.25W	Panasonic	ERJPA3F1103V
27	1	R35	N.M.	N.M.	N.M.	N.M.
28	1	T1	125uH	Transformer for BMS	WE	74941000
29	1	U1	L9963T, SO-16	Automotive general purpose SPI to isolated SPI transceiver	ST	<a href="#">L9963T</a>
30	1	U2	USBL6-2SC6Y2, SOT23-6L	Automotive ESD protection for high speed interfaces.	ST	<a href="#">USBL6-2SC6Y</a>

Item	Q.ty	Ref.	Part/Value	Description	Manufacturer	Order code
31	7	for blister	60900213421	WR-PHD 2.54 mm Multi-Jumper Jumper with Test Point	WE	60900213421
32	2	for blister	61900411621	WR-WTB 2.54 mm Female Terminal Housing	WE	61900411621
33	1	for blister	61900711621	WR-WTB 2.54 mm Female Terminal Housing	WE	61900711621
34	16	for blister	61910113722	WR-WTB 2.54 mm Female Crimp Contact	WE	61910113722
35	4	for blister	970080365	WA-SPAI Plastic Spacer Stud, metric, internal/ internal	WE	970080365
36	4	for blister	97790403111	WA-SCRW Pan Head Screw w. cross slot M3	WE	97790403111

## 10 Board versions

Table 8. AEK-COM-ISOSPI1 versions

Finished good	Schematic diagrams	Bill of materials
AEK\$COM-ISOSPI1A <sup>(1)</sup>	AEK\$COM-ISOSPI1A schematic diagrams	AEK\$COM-ISOSPI1A bill of materials

1. This code identifies the AEK-COM-ISOSPI1 evaluation board first version.

## 11 Regulatory compliance information

### Notice for US Federal Communication Commission (FCC)

For evaluation only; not FCC approved for resale

FCC NOTICE - This kit is designed to allow:

(1) Product developers to evaluate electronic components, circuitry, or software associated with the kit to determine

whether to incorporate such items in a finished product and

(2) Software developers to write software applications for use with the end product.

This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter 3.1.2.

### Notice for Innovation, Science and Economic Development Canada (ISED)

For evaluation purposes only. This kit generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to Industry Canada (IC) rules.

À des fins d'évaluation uniquement. Ce kit génère, utilise et peut émettre de l'énergie radiofréquence et n'a pas été testé pour sa conformité aux limites des appareils informatiques conformément aux règles d'Industrie Canada (IC).

### Notice for the European Union

This device is in conformity with the essential requirements of the Directive 2014/30/EU (EMC) and of the Directive 2015/863/EU (RoHS).

### Notice for the United Kingdom

This device is in compliance with the UK Electromagnetic Compatibility Regulations 2016 (UK S.I. 2016 No. 1091) and with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment Regulations 2012 (UK S.I. 2012 No. 3032).



## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
14-Jun-2023	1	Initial release.

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